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Finish review

Started on	Wednesday, 3 March 2021, 11:24 AM
State	Finished
Completed on	Wednesday, 3 March 2021, 11:29 AM
Time taken	5 mins 33 secs
Grade	6.50 out of 10.00 (65%)

Question 1

Incorrect

Mark 0.00 out of 1.00

Flag question

In our laboratory, the aluminum wiring is created by using _____ bonding technique at room temperature.

- ☐ a. eutectic
- ☐ b. ultrasonic
- ☐ c. vaporizing
- ☐ d. melting
- ☐ e. supersonic

Your answer is incorrect.

Question 2

Correct

Mark 1.00 out of 1.00

Flag question

The gold-silicon compound used in the post process is in _____ compound/liquid phase.

- ☐ a. melting
- ☐ b. fragmented
- ☒ c. eutectic point
- ☐ d. vaporizing
- ☐ e. plasma

Your answer is correct.

Question 3

Correct

Mark 1.00 out of 1.00

Flag question

What is the typical wafer diameter in the labs of DED?

- ☐ a. 5 inch
- ☐ b. 10 inch
- ☐ c. 20 cm
- ☐ d. 10 cm
- ☒ e. 2 inch

Your answer is correct.

Question 4

Complete

Mark 1.00 out of 1.00

Flag question

What does class 10000 clean room mean?

10000 clean room means that particles which diameter is less than 0.5 micrometers their number is needed to be less than 10000

Comment:

Question 5

Correct

Mark 1.00 out of 1.00

What is the pressure difference between the cleanroom and the outside of the lab?

- ☐ a. -50 Pa

1.00

Flag question

- ☒ b. 30 Pa
- ☐ c. 100 kPa
- ☐ d. 100 Pa
- ☐ e. 500 Pa



Your answer is correct.

Question 6

Correct

Mark 1.00 out of 1.00

Flag question

What is the wavelength of photolithography in the labs of DED?

- ☒ a. 465 nm
- ☐ b. 13.5 nm
- ☐ c. 0.1 μm
- ☐ d. 50 nm
- ☐ e. 1 μm



Your answer is correct.

Question 7

Incorrect

Mark 0.00 out of 1.00

Flag question

What kind of high temperature process can we do with our furnaces?

- ☐ a. Ion implantation
- ☐ b. Diffusion
- ☒ c. Sputtering
- ☒ d. Epitaxial layer growth
- ☐ e. Oxidation



Your answer is incorrect.

Question 8

Partially correct

Mark 0.50 out of 1.00

Flag question

The dicing saw has an air-bearing design, which is needed because:

- ☒ a. RPM is too high.
- ☒ b. the wafer is positioned using vacuum.
- ☐ c. the vibration of the environment need to be damped.
- ☐ d. the temperature is too high.
- ☐ e. otherwise the dust particles may contaminate the equipment.



Your answer is partially correct.

You have correctly selected 1.

Question 9

Correct

Mark 1.00 out of 1.00

Flag question

The diamond cutter uses to fix the wafer on the cutting table.

Your answer is correct.

Question 10

Incorrect

Mark 0.00 out of 1.00

Flag question

Which one is cleaner: ISO class 6 or class 7?

- ☒ a. Class 7
- ☐ b. Class 6



Your answer is incorrect.

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Finish review

Started on	Wednesday, 3 March 2021, 10:58 AM
State	Finished
Completed on	Wednesday, 3 March 2021, 11:09 AM
Time taken	11 mins 20 secs
Grade	8.33 out of 10.00 (83%)

Question 1

Correct

Mark 1.00 out of 1.00

Flag question

The diamond cutter uses the

middle of the frame

 to position the wafer.

Your answer is correct.

Question 2

Correct

Mark 1.00 out of 1.00

Flag question

What is the temperature accuracy of our hotplate?

- ☒ a. $\pm 2\text{ }^{\circ}\text{C}$
- ☐ b. $\pm 10\text{ }^{\circ}\text{C}$
- ☐ c. $\pm 20\text{ }^{\circ}\text{C}$
- ☐ d. $\pm 0.2\text{ }^{\circ}\text{C}$



Your answer is correct.

Question 3

Correct

Mark 1.00 out of 1.00

Flag question

Which one is cleaner: ISO class 6 or class 7?

- ☒ a. Class 6
- ☐ b. Class 7



Your answer is correct.

Question 4

Correct

Mark 1.00 out of 1.00

Flag question

What is the pressure difference between the cleanroom and the outside of the lab?

- ☒ a. 30 Pa
- ☐ b. 100 Pa
- ☐ c. 100 kPa
- ☐ d. -50 Pa
- ☐ e. 500 Pa



Your answer is correct.

Question 5

Correct

Mark 1.00 out of 1.00

Flag question

How do we set the desired thickness of the photoresist?

- ☒ a. Speed
- ☒ b. Time
- ☐ c. Temperature
- ☒ d. RPM
- ☐ e. PWM
- ☐ f. Wavelength



Your answer is correct.

Question 6

Correct

Mark 1.00 out of 1.00

Flag question

The diamond cutter uses

vacuum

 to fix the wafer on the cutting table.

Your answer is correct.

Question 7

Correct

Mark 1.00 out of 1.00

Flag question

The space between the chips on the wafer, where the dicing will happen is called ____.

- ☐ a. cutter plane.
- ☐ b. Intel road.
- ☐ c. dicing highway.
- ☐ d. cross-section.
- ☒ e. dicing street.



Your answer is correct.

Question 8

Partially correct

Mark 0.33 out of 1.00

Flag question

What does the bunny suit made of?

- ☐ a. flokon
- ☐ b. batist
- ☐ c. kevlar
- ☐ d. metal fiber
- ☐ e. wool
- ☐ f. carbon
- ☒ g. syntethic fiber
- ☐ h. silk



Your answer is partially correct.

You have correctly selected 1.

Question 9

Incorrect

Mark 0.00 out of 1.00

Flag question

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Mark 1.00 out of 1.00

Flag question

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- ☐ a. 0.1 μm
- ☒ b. 465 nm
- ☐ c. 1 μm
- ☐ d. 13.5 nm
- ☐ e. 50 nm



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- ☒ a. ± 2 °C
- ☐ b. ± 10 °C
- ☐ c. ± 20 °C
- ☐ d. ± 0.2 °C

Your answer is correct.

Question 3

Correct

Mark 1.00 out of 1.00

Flag question

Which one is cleaner: ISO class 6 or class 7?

- ☒ a. Class 6
- ☐ b. Class 7

Your answer is correct.

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Correct

Mark 1.00 out of 1.00

Flag question

What is the pressure difference between the cleanroom and the outside of the lab?

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Flag question

How do we set the desired thickness of the photoresist?

- ☒ a. Speed
- ☒ b. Time
- ☐ c. Temperature
- ☒ d. RPM
- ☐ e. PWM
- ☐ f. Wavelength

Your answer is correct.

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Correct

Mark 1.00 out of 1.00

Flag question

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Mark 1.00 out of 1.00

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- ☐ c. dicing highway.
- ☐ d. cross-section.
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Mark 0.33 out of 1.00

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- ☐ d. metal fiber
- ☐ e. wool
- ☐ f. carbon
- ☒ g. syntethic fiber
- ☐ h. silk



Your answer is partially correct.

You have correctly selected 1.

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Mark 0.00 out of 1.00

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- ☐ d. ultrasonic
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Mark 1.00 out of 1.00

Flag question

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- ☒ b. 465 nm
- ☐ c. 1 μm
- ☐ d. 13.5 nm
- ☐ e. 50 nm

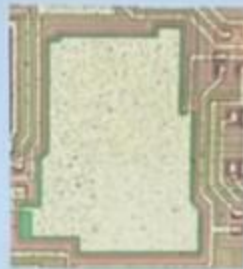


Your answer is correct.

Finish review

What type of electronic component can you see on the image?

What type of electronic component can you see on the image?



Select one or more:

- ☐ a. transistor
- ☐ b. resistor
- ☒ c. capacitor
- ☐ d. diode

What type of electronic component can you see on the image?

What type of electronic component can you see on the image?



Select one or more:

- ☒ a. capacitor
- ☐ b. transistor
- ☐ c. resistor
- ☐ d. diode

Активация Windows

Чтобы активировать Windows, перейдите в раздел "Параметры"

What type of electronic component can you see on the image?



Select one or more:

- ☐ a. diode
- ☐ b. capacitor
- ☐ c. transistor
- ☒ d. resistor

Question 17

Correct

Mark 1.00 out of 1.00

Flag question

What type of electronic component can you see on the image?



Select one or more:

- ☐ a. transistor
- ☐ b. diode
- ☐ c. resistor
- ☒ d. capacitor

Активация Windows

Чтобы активировать Windows, перейдите в раздел "Параметры".

- ☐ c. resistor
- ☒ d. transistor

Question 15

Correct

Mark 1.00 out of 1.00

Flag question

What type of electronic component can you see on the image?

What type of electronic component can you see on the image?



Select one or more:

- ☐ a. capacitor
- ☒ b. transistor
- ☐ c. resistor
- ☐ d. diode

Question 16

Correct

Mark 1.00 out of 1.00

Flag question

What type of electronic component can you see on the image?

What type of electronic component can you see on the image?



Активация Windows

Чтобы активировать Windows, перейдите в раздел "Параметры"

Question 13
Correct
Mark 1.00 out of 1.00
Flag question

What type of electronic component can you see on the image?

What type of electronic component can you see on the image?



Select one or more:

- ☐ a. capacitor
- ☐ b. diode
- ☒ c. resistor
- ☐ d. transistor

Question 14
Correct
Mark 1.00 out of 1.00
Flag question

What type of electronic component can you see on the image?

What type of electronic component can you see on the image?

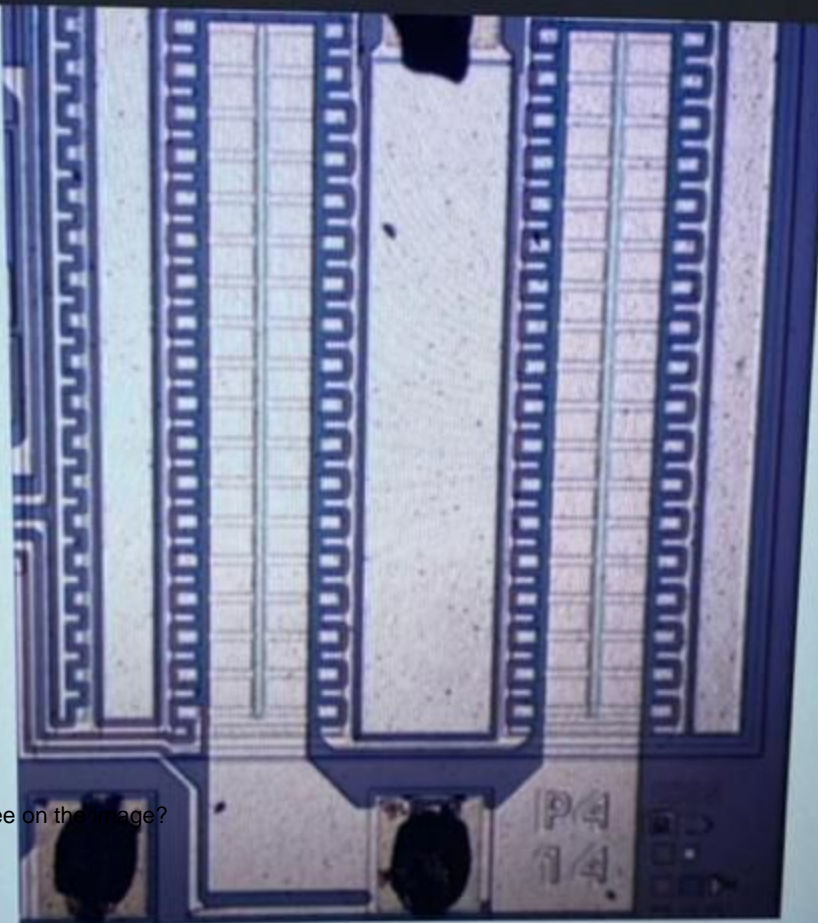


Select one or more:

- ☒ a. diode
- ☐ b. capacitor
- ☐ c. resistor
- ☐ d. transistor

Активация Windows

Чтобы активировать Windows, перейдите в раздел "Параметры".



What type of electronic component can you see on the image?

Select one or more:

- ☐ a. diode
- ☐ b. resistor
- ☐ c. capacitor
- ☒ d. transistor

Активация Windows

Чтобы активировать Windows, перейдите в раздел "Параметры".

Question 11

Correct

Mark 1.00 out of 1.00

Flag question

What type of electronic component can you see on the image?

What type of electronic component can you see on the image?



Select one or more:

- ☐ a. capacitor
- ☒ b. resistor
- ☐ c. diode
- ☐ d. transistor

Question 12

Correct

Mark 1.00 out of 1.00

Flag question

What type of electronic component can you see on the image?

What type of electronic component can you see on the image?



Активация Windows

Чтобы активировать Windows, перейдите в раздел "Активация".

Question 9
Incorrect
Mark 0.00 out of 1.00
Flag question

What type of electronic component can you see on the image?

What type of electronic component can you see on the image?



Select one or more:

- ☐ a. resistor
- ☒ b. transistor
- ☐ c. capacitor
- ☐ d. diode

Question 10
Incorrect
Mark 0.00 out of 1.00
Flag question

What type of electronic component can you see on the image?



Select one or more:

- ☐ a. capacitor
- ☒ b. resistor
- ☐ c. diode
- ☐ d. transistor

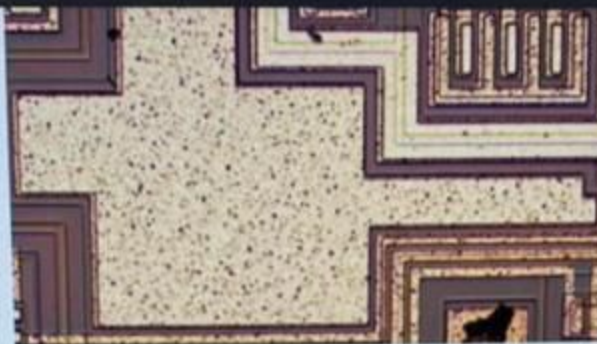
Активация Windows

Чтобы активировать Windows, перейдите в раздел "Параметры"

Question 11
Correct

What type of electronic component can you see on the image?





Select one or more:

- ☐ a. diode
- ☐ b. resistor
- ☒ c. capacitor
- ☐ d. transistor

What type of electronic component can you see on the image?

What type of electronic component can you see on the image?



Select one or more:

- ☒ a. transistor
- ☐ b. diode
- ☐ c. capacitor
- ☐ d. resistor

Активация Windows

Чтобы активировать Windows, перейдите в раздел "Параметры"

What type of electronic component can you see on the image?



What type of electronic component can you see on the image?

Select one or more:

- ☐ a. capacitor
- ☐ b. diode
- ☐ c. transistor
- ☒ d. resistor

What type of electronic component can you see on the image?



Select one or more:

- ☐ a. resistor
- ☒ b. capacitor

Активация Windows

Чтобы активировать Windows, перейдите в раздел "Параметры".

Mark 1.00 out of 1.00

Flag question



Select one or more:

- ☐ a. transistor
- ☐ b. diode
- ☐ c. capacitor
- ☒ d. resistor

What type of electronic component can you see on the image?

✓

Question 4

Correct

Mark 1.00 out of 1.00

Flag question

What type of electronic component can you see on the image?



Select one or more:

- ☐ a. resistor
- ☒ b. transistor
- ☐ c. diode
- ☐ d. capacitor

Активация Windows

Нужно активировать Windows. Перейдите в меню "Параметры".

✓

+

Time taken 45 mins 50 secs
Grade 17.00 out of 19.00 (89%)

Question 1
Incorrect
Mark 1.00 out of 1.00
Flag question

What type of electronic component can you see on the image?



Select one or more:

- ☐ a. transistor
- ☐ b. diode
- ☒ c. resistor
- ☐ d. capacitor

What type of electronic component can you see on the image?

Question 2
Incorrect
Mark 0.00 out of 1.00
Flag question

What type of electronic component can you see on the image?



Select one or more:

- ☐ a. resistor
- ☒ b. transistor
- ☐ c. capacitor
- ☐ d. diode

Активация Windows

Чтобы активировать Windows, зайдите на сайт <http://go.microsoft.com/fwlink/?LinkId=268619>

Question 3
What type of electronic component can you see on the image?

Started on	Wednesday, 10 March 2021, 11:49 AM
State	Finished
Completed on	Wednesday, 10 March 2021, 11:53 AM
Time taken	4 mins 16 secs
Grade	7.00 out of 7.00 (100%)

Question 1

Correct

Mark 1.00 out of 1.00

Flag question

When the thermal boundary of the virtual system is set that the heat cannot be transferred through the given boundary, then it is called:

- ☐ a. Propagating
 - ☐ b. Conductive
 - ☐ c. Isothermal
 - ☒ d. Adiabatic
- ✓

Your answer is correct.

Question 2

Correct

Mark 1.00 out of 1.00

Flag question

What does the value of R_{thjc} thermal resistance show?

- ☒ a. The thermal resistance between the active (dissipating) zone and the inner edge of the top of the package.
 - ☐ b. The thermal resistance between the active (dissipating) zone and the ambient.
 - ☐ c. The thermal resistance between the top and the bottom of the case.
 - ☐ d. The thermal resistance between the active (dissipating) zone and the PCB board.
- ✓

Your answer is correct.

Question 3

Correct

Mark 1.00 out of 1.00

Flag question

What is the unit of thermal resistance?

- ☐ a. W/K
 - ☐ b. K-W/s
 - ☐ c. W-s/K
 - ☒ d. K/W
- ✓

Your answer is correct.

Question 4

Correct

Mark 1.00 out of 1.00

Flag question

What is the unit of thermal conductance?

- ☐ a. K/W
 - ☐ b. K-W/s
 - ☒ c. W/K
 - ☐ d. W-s/K
- ✓

Your answer is correct.

Question **5**

Correct

Mark 1.00 out of 1.00

Flag question

What does the value of R_{thca} thermal resistance show?

- ☐ a.
The thermal resistance between the active (dissipating) zone and the PCB board.
- ☐ b.
The thermal resistance between the top of the package and the ambient.
- ☒ c.
The thermal resistance between the active (dissipating) zone and the inner edge of the top of the package.
- ☐ d.
The thermal resistance between the active (dissipating) zone and the ambient.

Your answer is correct.

Question **6**

Correct

Mark 1.00 out of 1.00

Flag question

What is the unit of thermal capacitance?

- ☐ a.
K·W/s
- ☐ b.
W·s/K
- ☒ c.
W·m/K
- ☐ d.
s·K/W

Your answer is correct.

Question **7**

Correct

Mark 1.00 out of 1.00

Flag question

What is the R_{thja} thermal resistance value of a DIL package with a supply voltage of 3V and with an average current of 0.5A, if there is a 30°C temperature difference between the dissipating region and the outside of the package?

- ☐ a.
13,33 mK/W
- ☐ b.
30 W/K
- ☐ c.
20 K/W
- ☒ d.
0.05 K/W

Your answer is correct.

Finish review

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Finish review